

--57. The device according to claim 56, in which the attachment material is one of a polymer, a frit and a metal.--

--58. The device according to claim 57, in which the polymer is an epoxy adhesive.--

O--59. The device according to claim 55, further comprising a bonding pad having a coefficient of expansion intermediate between that of the fiber and the substrate mounted between the optical fiber and the substrate at each of the first and second locations, the optical fiber being bonded to each bonding pad and each bonding pad being affixed to the substrate.--

--60. Apparatus comprising:

- (a) a substrate having a negative coefficient of thermal expansion;
and
- (b) a fiber grating affixed to the substrate.--

--61. In an apparatus having a fiber grating affixed to a device where the device provides thermal compensation to the fiber grating, the improvement wherein the device comprises a material having a negative coefficient of thermal expansion.--

REMARKS

This is a continuation of co-pending application number 09/101,630, filed July 14, 1998, which is the U.S. national phase filing of PCT/US96/13062 filed on August 7, 1996.

This application is being filed for the purposes of provoking an interference with Fleming et al., U.S. Patent No. 5,694,503, which issued on December 2, 1997.

Applicant is preparing the information called for by 37 CFR §1.607(a) and will submit that information when completed.

No additional claim fees beyond those submitted herewith are believed to be necessary for the entry of this preliminary amendment. However, if such fees are required, the Commissioner is hereby authorized to charge the fees to Deposit Account No. 11-1158.

Respectfully submitted,

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